

Title (en)  
HEAT-BONDABLE COMPOSITE FIBER AND PROCESS FOR PRODUCING THE SAME

Title (de)  
THERMOBONDIERBARE VERBUNDFASER UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)  
FIBRE COMPOSITE THERMOUSOUDABLE ET SON PROCÉDÉ DE PRODUCTION

Publication  
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Application  
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Abstract (en)  
[origin: EP2022877A1] An essential object of the invention is to provide a low-modulus, self-extensible thermal-adhesive bicomponent fiber comprising polyethylene terephthalate as the fiber-forming resin component thereof and capable of producing a nonwoven fabric or a fiber structure that has a high adhesive strength and is bulky and well drapable. The object of the invention is attained by a self-extensible thermal-adhesive bicomponent fiber that comprises a fiber-forming resin component and a thermal-adhesive resin component and is characterized in that the fiber-forming resin component comprises polyethylene terephthalate, that the thermal-adhesive resin component comprises a crystalline thermoplastic resin having a melting point lower by at least 20°C than that of the fiber-forming resin component, and that its breaking elongation is from 130 to 600 %, its 100 % elongation tensile strength is from 0.3 to 1.0 cN/dtex and its 120°C dry heat shrinkage is smaller than -1.0 %; and by a method for producing it.

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